

**Maximum Ratings** 

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{\sf CEO}$	50	V
Collector-base voltage	$V_{\mathrm{CBO}}$	50	
Input forward voltage	V <sub>i(fwd)</sub>	60	
Input reverse voltage	V <sub>i(rev)</sub>	10	
Collector current	I <sub>C</sub>	100	mA
Total power dissipation-	$P_{tot}$		mW
BCR141, <i>T</i> <sub>S</sub> ≤ 118°C		250	
BCR141F, <i>T</i> <sub>S</sub> ≤ 128°C		250	
BCR141S, <i>T</i> <sub>S</sub> ≤ 115°C		250	
BCR141W, <i>T</i> <sub>S</sub> ≤ 124°C		250	
Junction temperature	T <sub>i</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-65 150	

#### **Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	R <sub>thJS</sub>		K/W
BCR141		≤ 130	
BCR141F		≤ 90	
BCR141S		≤ 140	
BCR141W		≤ 133	

 $<sup>^{1}</sup>$ For calculation of  $R_{thJA}$  please refer to Application Note Thermal Resistance



**Electrical Characteristics** at  $T_A = 25$ °C, unless otherwise specified **Symbol Values** Unit **Parameter** min. typ. max. **DC Characteristics** ٧  $V_{(BR)CEO}$ 50 Collector-emitter breakdown voltage  $I_{\rm C} = 100 \, \mu \text{A}, \, I_{\rm B} = 0$ Collector-base breakdown voltage  $V_{(BR)CBO}$ 50  $I_{\rm C} = 10 \ \mu {\rm A}, \ I_{\rm E} = 0$ Collector-base cutoff current 100 nΑ *I*<sub>CBO</sub> - $V_{\rm CB} = 40 \text{ V}, I_{\rm E} = 0$ 350 μΑ Emitter-base cutoff current *I*EBO  $V_{\rm EB} = 10 \text{ V}, I_{\rm C} = 0$ DC current gain<sup>1)</sup> 50  $h_{\mathsf{FE}}$  $I_{\rm C} = 5 \text{ mA}, \ V_{\rm CE} = 5 \text{ V}$ Collector-emitter saturation voltage<sup>1)</sup> ٧ V<sub>CEsat</sub> 0.3  $I_{\rm C} = 10 \text{ mA}, I_{\rm B} = 0.5 \text{ mA}$ Input off voltage  $V_{i(off)}$ 8.0 1.5  $I_{\rm C} = 100 \,\mu{\rm A}, \, V_{\rm CE} = 5 \,\rm V$ Input on voltage  $V_{i(on)}$ 1 2.5  $I_{\rm C} = 2 \text{ mA}, \ V_{\rm CE} = 0.3 \text{ V}$  $R_1$ 29 Input resistor 15 22  $\mathsf{k}\Omega$ Resistor ratio  $R_1/R_2$ 0.9 1 1.1 **AC Characteristics**  $f_{\mathsf{T}}$ MHz Transition frequency 130  $I_{\rm C} = 10 \text{ mA}, V_{\rm CE} = 5 \text{ V}, f = 100 \text{ MHz}$ рF Collector-base capacitance 3  $C_{cb}$ 

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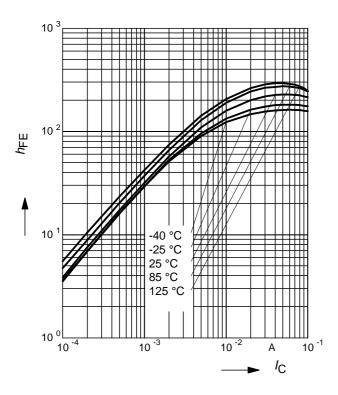
 $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$ 

<sup>&</sup>lt;sup>1</sup>Pulse test:  $t < 300\mu s$ ; D < 2%



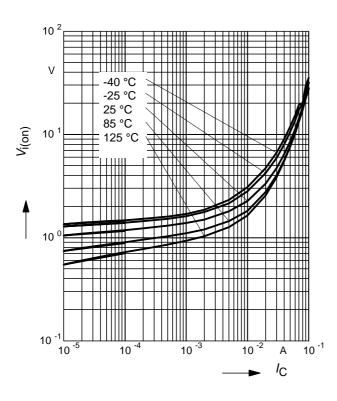
## **DC** current gain $h_{FE} = f(I_C)$

 $V_{CE} = 5 \text{ V (common emitter configuration)}$ 



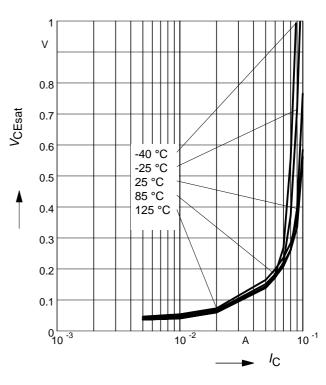
Input on Voltage  $Vi_{(On)} = f(I_C)$ 

 $V_{CE} = 0.3V$  (common emitter voltage)



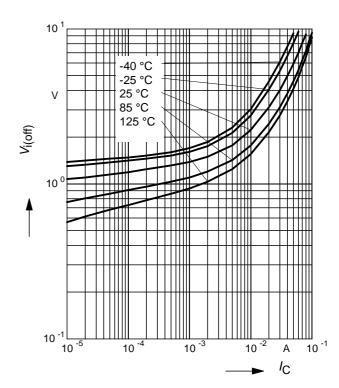
#### Collector-emitter saturation voltage

 $V_{CEsat} = f(I_{C}), I_{C}/I_{B} = 20$ 



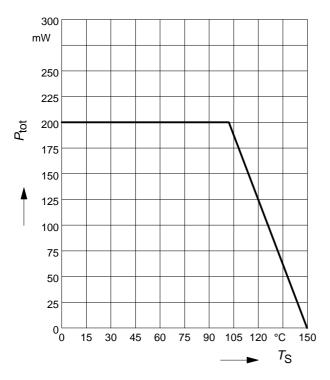
Input off voltage  $V_{i(Off)} = f(I_C)$ 

 $V_{CE} = 5V$  (common emitter voltage)

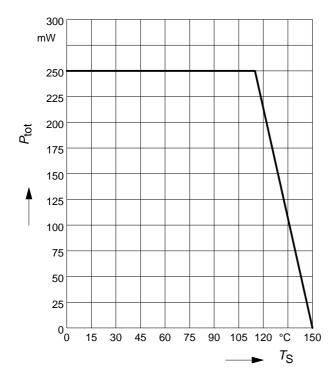




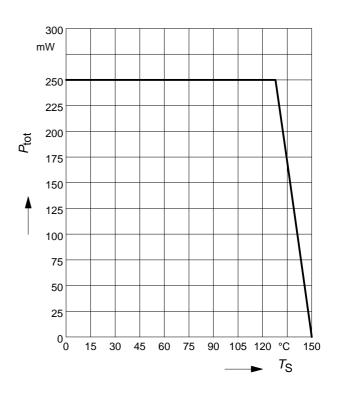
## **Total power dissipation** $P_{tot} = f(T_S)$ BCR141



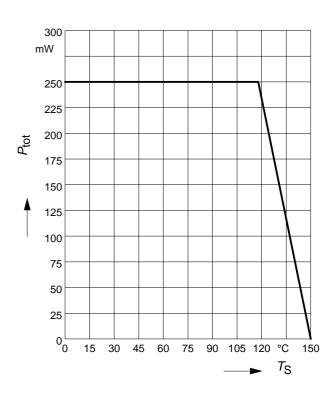
**Total power dissipation**  $P_{tot} = f(T_S)$  BCR141S



Total power dissipation  $P_{tot} = f(T_S)$  BCR141F

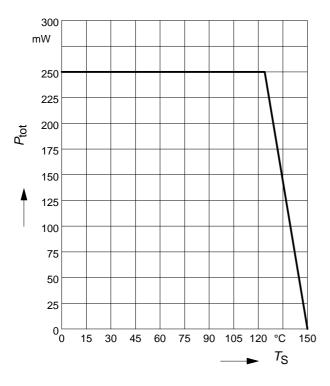


**Total power dissipation**  $P_{tot} = f(T_S)$  BCR141U



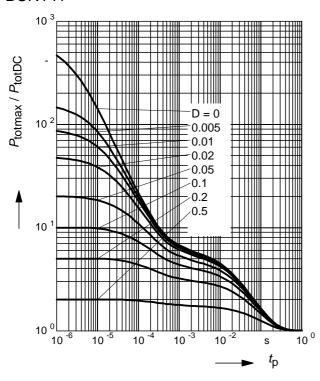


## Total power dissipation $P_{tot} = f(T_S)$ BCR141W

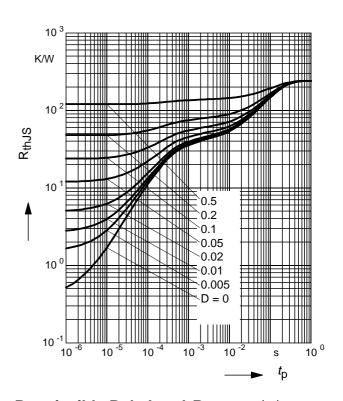


#### **Permissible Pulse Load**

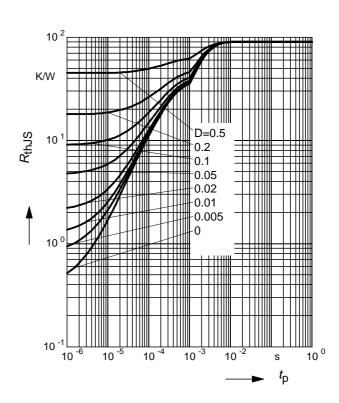
 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR141



## **Permissible Pulse Load** $R_{thJS} = f(t_p)$ BCR141



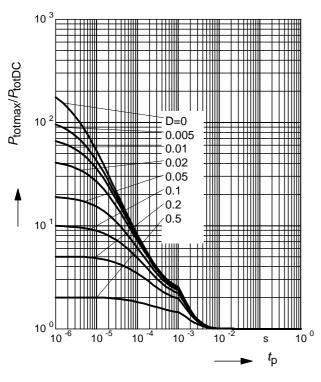
**Permissible Puls Load**  $R_{thJS} = f(t_p)$  BCR141F



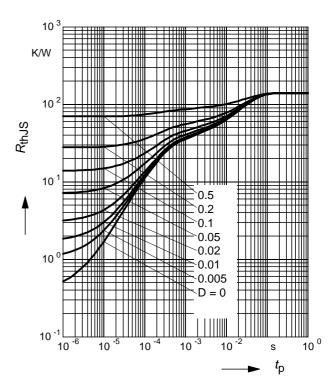


#### **Permissible Pulse Load**

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR141F

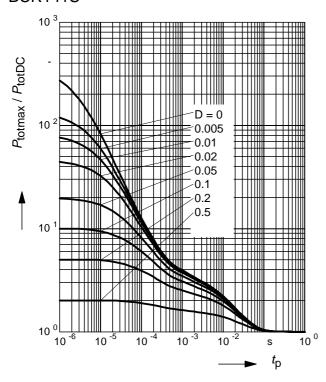


# Permissible Puls Load $R_{thJS} = f(t_p)$ BCR141S

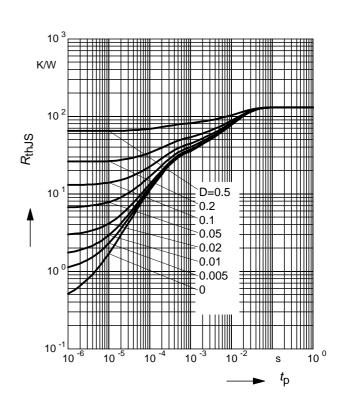


#### **Permissible Pulse Load**

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$ BCR141S



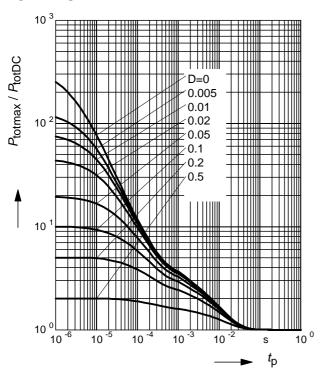
**Permissible Puls Load**  $R_{thJS} = f(t_p)$  BCR141U



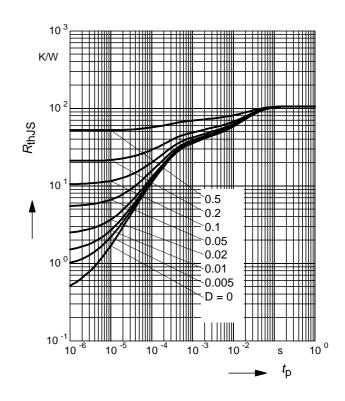


#### **Permissible Pulse Load**

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$ BCR141U

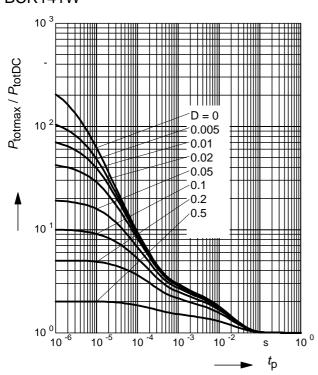


## **Permissible Puls Load** $R_{thJS} = f(t_p)$ BCR141W

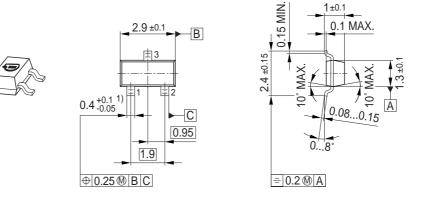


#### **Permissible Pulse Load**

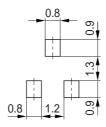
 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR141W





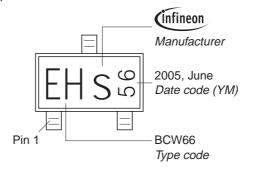


Foot Print



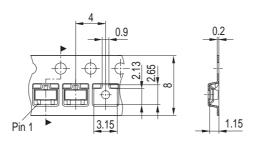
1) Lead width can be 0.6 max. in dambar area

## Marking Layout (Example)



## Standard Packing

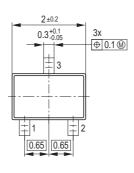
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

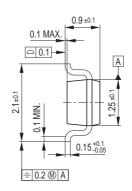


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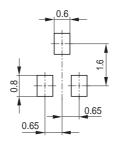




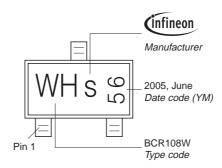




#### Foot Print

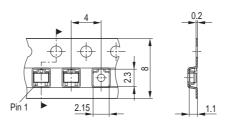


## Marking Layout (Example)

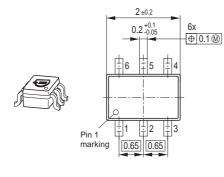


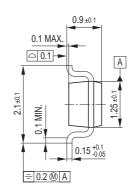
## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

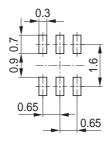






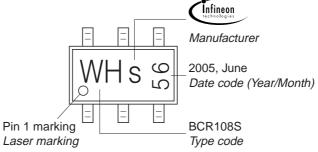


#### Foot Print



## Marking Layout (Example)

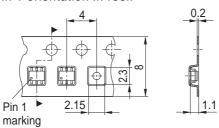
Small variations in positioning of Date code, Type code and Manufacture are possible.



## Standard Packing

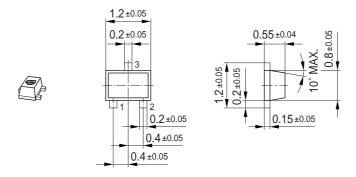
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.

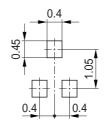


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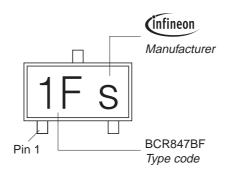




#### Foot Print

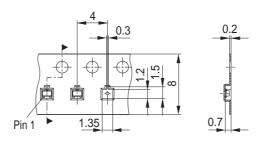


## Marking Layout (Example)



## Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel





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